



ALLENIG4.001AUS

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant : Kripesh et al.  
Appl. No. : 10/078,243  
Filed : February 14, 2002  
For : PROCESS OF FORMING METAL  
SURFACES COMPATIBLE WITH  
A WIRE BONDING AND  
SEMICONDUCTOR  
INTEGRATED CIRCUITS  
MANUFACTURED BY THE  
PROCESS  
Examiner : L. A. Gurley  
Group Art Unit : 2812

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 8, 2004

(Date)

John M. Carson, Reg. No. 34,303

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed October 8, 2003, Applicant respectfully submits the following amendments and remarks in connection with the above-captioned application.

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 5 of this paper.

**Remarks/Arguments** begin on page 14 of this paper.

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